Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	2304
Total RAM Bits	18432
Number of I/O	289
Number of Gates	50000
Voltage - Supply	3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C
Package / Case	352-LBGA
Supplier Device Package	352-SBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at40k40al-1bgc

Table 1. AT40KAL Family[1]

Device	AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL
Usable Gates	5K - 10K	10K - 20K	20K - 30K	40K - 50K
Rows x Columns	16 x 16	24 x 24	32 x 32	48 x 48
Cells	256	576	1,024	2,304
Registers	496[1]	954[1]	1,520[1]	3,048[1]
RAM Bits	2,048	4,608	8,192	18,432
I/O (Maximum)	128	192	256	384

Note: 1. Packages with FCK will have 8 less registers.

Description

The AT40KAL is a family of fully PCI-compliant, SRAM-based FPGAs with distributed 10 ns programmable synchronous/asynchronous, dual-port/single-port SRAM, 8 global clocks, Cache Logic ability (partially or fully reconfigurable without loss of data), automatic component generators, and range in size from 5,000 to 50,000 usable gates. I/O counts range from 128 to 384 in industry standard packages ranging from 84-pin PLCC to 352-ball Square BGA, and support 3.3V designs.

The AT40KAL is designed to quickly implement high-performance, large gate count designs through the use of synthesis and schematic-based tools used on a PC or Sun platform. Atmel's design tools provide seamless integration with industry standard tools such as Synplicity, ModelSim, Exemplar and Viewlogic. See the "IDS Datasheet" available on the Atmel web site (http://www.atmel.com/atmel/acrobat/doc1421.pdf) for a list of other supported tools.

The AT40KAL can be used as a coprocessor for high-speed (DSP/processor-based) designs by implementing a variety of computation intensive, arithmetic functions. These include adaptive finite impulse response (FIR) filters, fast Fourier transforms (FFT), convolvers, interpolators and discrete-cosine transforms (DCT) that are required for video compression and decompression, encryption, convolution and other multimedia applications.

Fast, Flexible and Efficient SRAM

The AT40KAL FPGA offers a patented distributed 10 ns SRAM capability where the RAM can be used without losing logic resources. Multiple independent, synchronous or asynchronous, dual-port or single-port RAM functions (FIFO, scratch pad, etc.) can be created using Atmel's macro generator tool.

Fast, Efficient Array and Vector Multipliers

The AT40KAL's patented 8-sided core cell with direct horizontal, vertical and diagonal cell-to-cell connections implements ultra fast array multipliers without using any busing resources. The AT40KAL's Cache Logic capability enables a large number of design coefficients and variables to be implemented in a very small amount of silicon, enabling vast improvement in system speed at much lower cost than conventional FPGAs.

Reading and writing of the 10 ns 32 x 4 dual-port FreeRAM are independent of each other. Reading the 32 x 4 dual-port RAM is completely asynchronous. Latches are transparent; when Load is logic 1, data flows through; when Load is logic 0, data is latched. These latches are used to synchronize Write Address, $\overline{\text{Write Enable Not}}$, and Din signals for a synchronous RAM. Each bit in the 32 x 4 dual-port RAM is also a transparent latch. The front-end latch and the memory latch together form an edge-triggered flip flop. When a nibble (bit = 7) is (Write) addressed and LOAD is logic 1 and $\overline{\text{WE}}$ is logic 0, data flows through the bit. When a nibble is not (Write) addressed or LOAD is logic 0 or $\overline{\text{WE}}$ is logic 1, data is latched in the nibble. The two CLOCK muxes are controlled together; they both select CLOCK (for a synchronous RAM) or they both select "1" (for an asynchronous RAM). CLOCK is obtained from the clock for the sector-column immediately to the left and immediately above the RAM block. Writing any value to the RAM clear byte during configuration clears the RAM (see the "AT40K/40KAL Configuration Series" application note at www.atmel.com).

Figure 8. RAM Logic

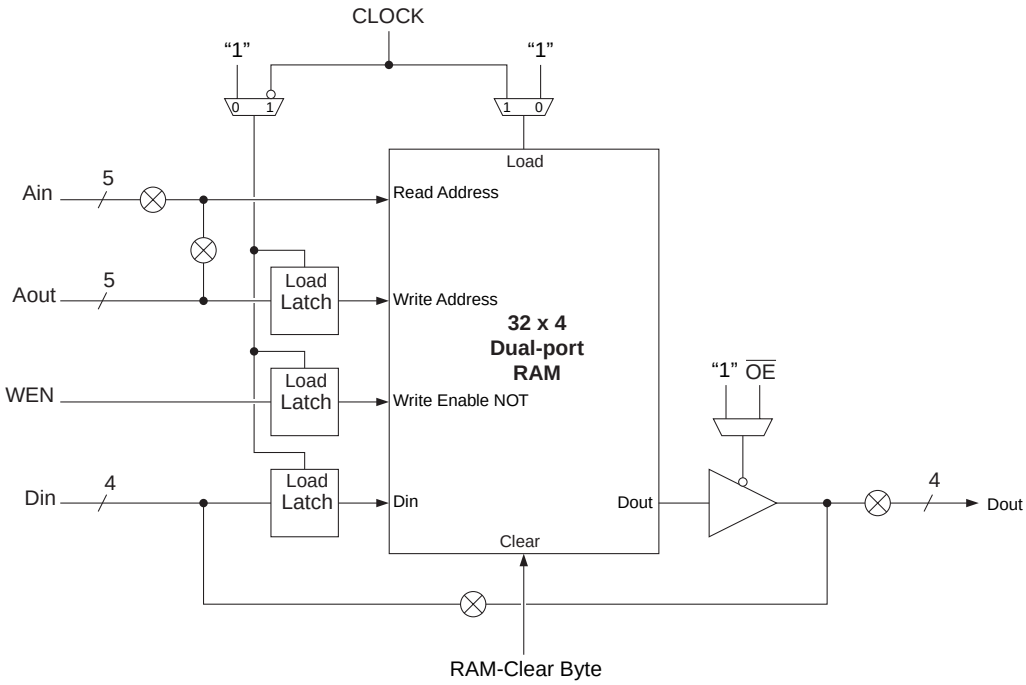
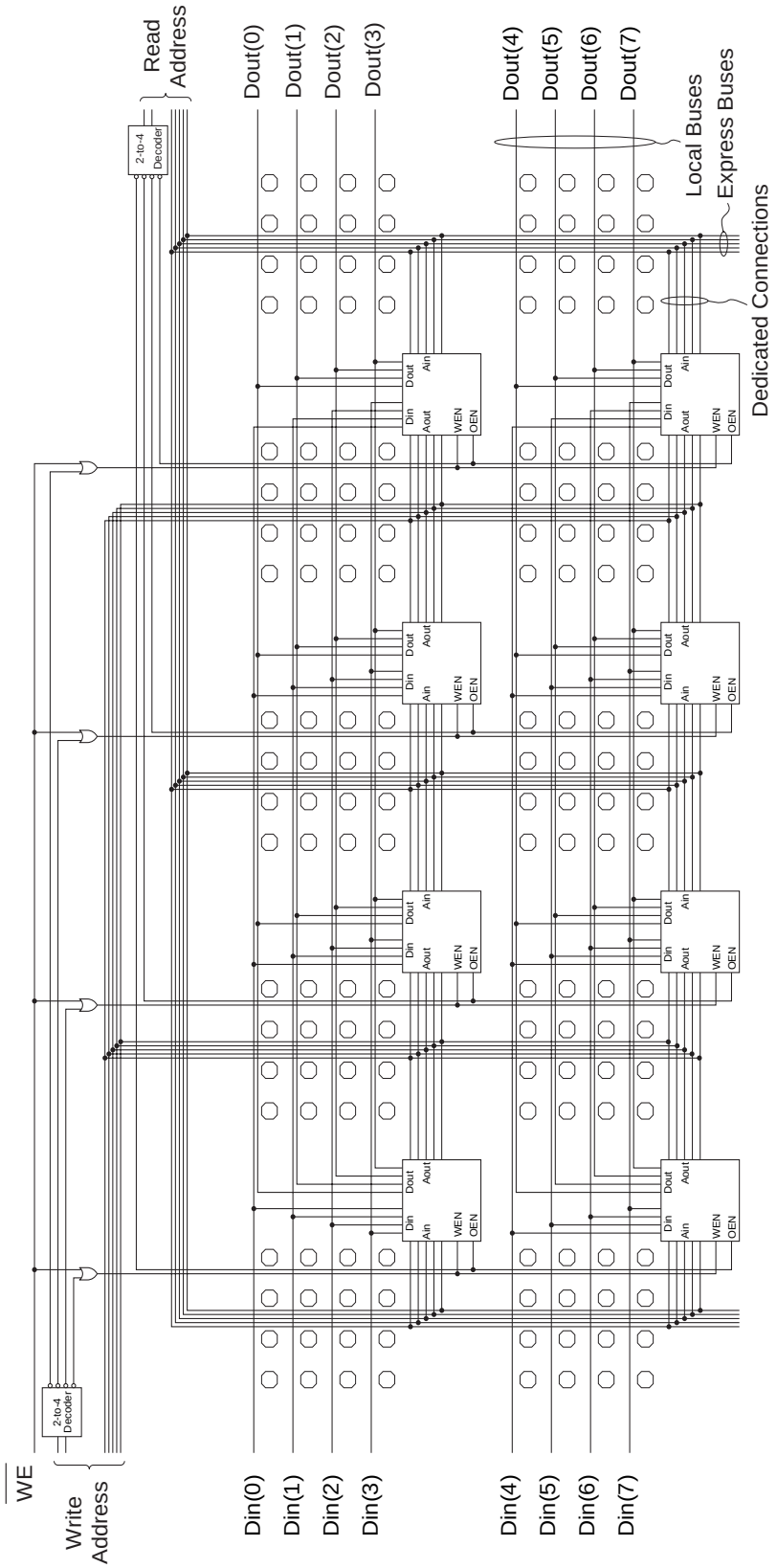


Figure 9 on page 13 shows an example of a RAM macro constructed using the AT40KAL's FreeRAM cells. The macro shown is a 128 x 8 dual-ported asynchronous RAM. Note the very small amount of external logic required to complete the address decoding for the macro. Most of the logic cells (core cells) in the sectors occupied by the RAM will be unused: they can be used for other logic in the design. This logic can be automatically generated using the macro generators.

Figure 9. RAM Example: 128 x 8 Dual-ported RAM (Asynchronous)



Clocking Scheme

There are eight Global Clock buses (GCK1 - GCK8) on the AT40KAL FPGA. Each of the eight dedicated Global Clock buses is connected to one of the dual-use Global Clock pins. Any clocks used in the design should use global clocks where possible: this can be done by using Assign Pin Locks to lock the clocks to the Global Clock locations. In addition to the eight Global Clocks, there are four Fast Clocks (FCK1 - FCK4), two per edge column of the array for PCI specification. For AT40KAL FPGAs, even the derived clocks can be routed through the Global network. Access points are provided in the corners of the array to route the derived clocks into the global clock network. The IDS software tools handle derived clocks to global clock connections automatically if used.

Each column of an array has a “Column Clock mux” and a “Sector Clock mux”. The Column Clock mux is at the top of every column of an array and the Sector Clock mux is at every four cells. The Column Clock mux is selected from one of the eight Global Clock buses. The clock provided to each sector column of four cells is inverted, non-inverted or tied off to “0”, using the Sector Clock mux to minimize the power consumption in a sector that has no clocks. The clock can either come from the Column Clock or from the Plane 4 express bus, see Figure 10 on page 15. The extreme-left Column Clock mux has two additional inputs, FCK1 and FCK2, to provide fast clocking to left-side I/Os. The extreme-right Column Clock mux has two additional inputs as well, FCK3 and FCK4, to provide fast clocking to right-side I/Os.

The register in each cell is triggered on a rising clock edge by default. Before configuration on power-up, constant “0” is provided to each register’s clock pins. After configuration on power-up, the registers either set or reset, depending on the user’s choice.

The clocking scheme is designed to allow efficient use of multiple clocks with low clock skew, both within a column and across the core cell array.

Set/Reset Scheme

The AT40KAL family reset scheme is essentially the same as the clock scheme except that there is only one Global Reset. A dedicated Global Set/Reset bus can be driven by any User I/O, except those used for clocking (Global Clocks or Fast Clocks). The automatic placement tool will choose the reset net with the most connections to use the global resources. You can change this by using an RSBUF component in your design to indicate the global reset. Additional resets will use the express bus network.

The Global Set/Reset is distributed to each column of the array. Like Sector Clock mux, there is Sector Set/Reset mux at every four cells. Each sector column of four cells is set/reset by a Plane 5 express bus or Global Set/Reset using the Sector Set/Reset mux, see Figure 11 on page 17. The set/reset provided to each sector column of four cells is either inverted or non-inverted using the Sector Reset mux.

The function of the Set/Reset input of a register is determined by a configuration bit in each cell. The Set/Reset input of a register is active low (logic 0) by default. Setting or Resetting of a register is asynchronous. Before configuration on power-up, a logic 1 (a high) is provided by each register (i.e., all registers are set at power-up).

I/O Structure

The AT40KAL has registered I/Os and group enable every sector for tri-states on obuf's.

PAD

The I/O pad is the one that connects the I/O to the outside world. Note that not all I/Os have pads: the ones without pads are called Unbonded I/Os. The number of unbonded I/Os varies with the device size and package. These unbonded I/Os are used to perform a variety of bus turns at the edge of the array.

PULL-UP/PULL-DOWN

Each pad has a programmable pull-up and pull-down attached to it. This supplies a weak "1" or "0" level to the pad pin. When all other drivers are off, this control will dictate the signal level of the pad pin.

The input stage of each I/O cell has a number of parameters that can be programmed either as properties in schematic entry or in the I/O Pad Attributes editor in IDS.

CMOS

The threshold level is a CMOS-compatible level.

SCHMITT

A Schmitt trigger circuit can be enabled on the inputs. The Schmitt trigger is a regenerative comparator circuit that adds 1V hysteresis to the input. This effectively improves the rise and fall times (leading and trailing edges) of the incoming signal and can be useful for filtering out noise.

DELAYS

The input buffer can be programmed to include four different intrinsic delays as specified in the AC timing characteristics. This feature is useful for meeting data hold requirements for the input signal.

DRIVE

The output drive capabilities of each I/O are programmable. They can be set to FAST, MEDIUM or SLOW (using IDS tool). The FAST setting has the highest drive capability (20 mA at 5V) buffer and the fastest slew rate. MEDIUM produces a medium drive (14 mA at 5V) buffer, while SLOW yields a standard (6 mA at 5V) buffer.

TRI-STATE

The output of each I/O can be made tri-state (0, 1 or Z), open source (1 or Z) or open drain (0 or Z) by programming an I/O's Source Selection mux. Of course, the output can be normal (0 or 1), as well.

SOURCE SELECTION MUX

The Source Selection mux selects the source for the output signal of an I/O.

Figure 12. West Primary I/O (Mirrored for East I/O)

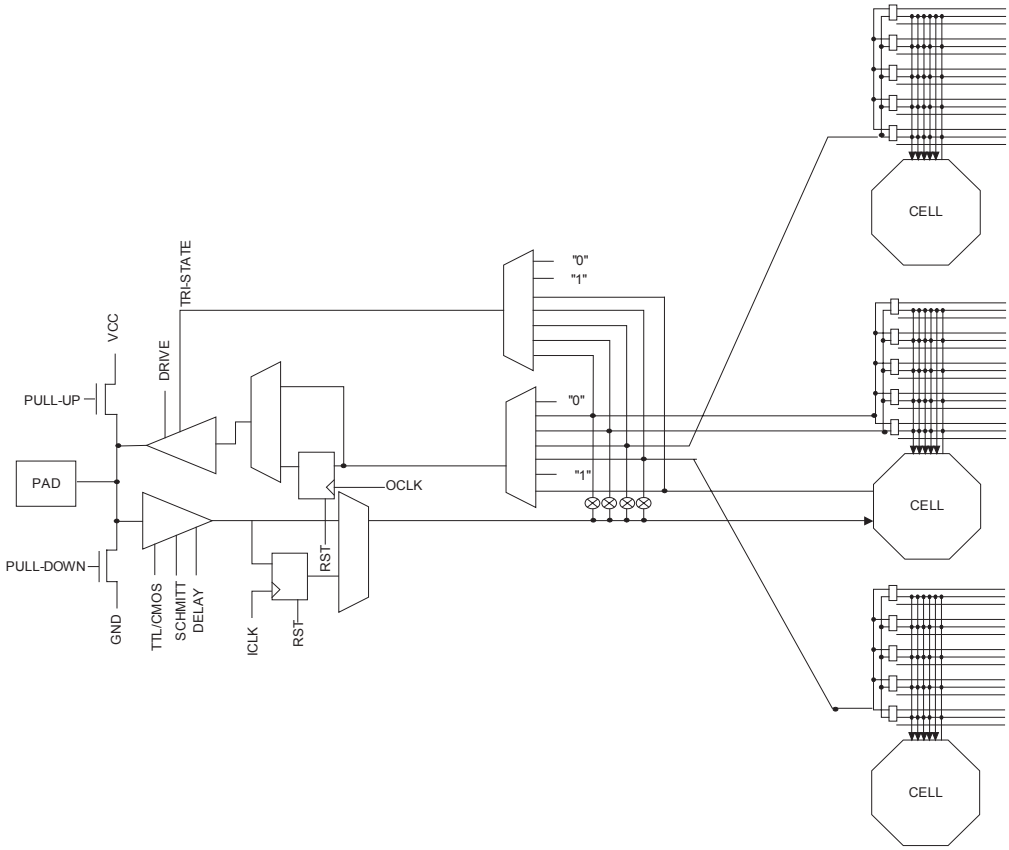
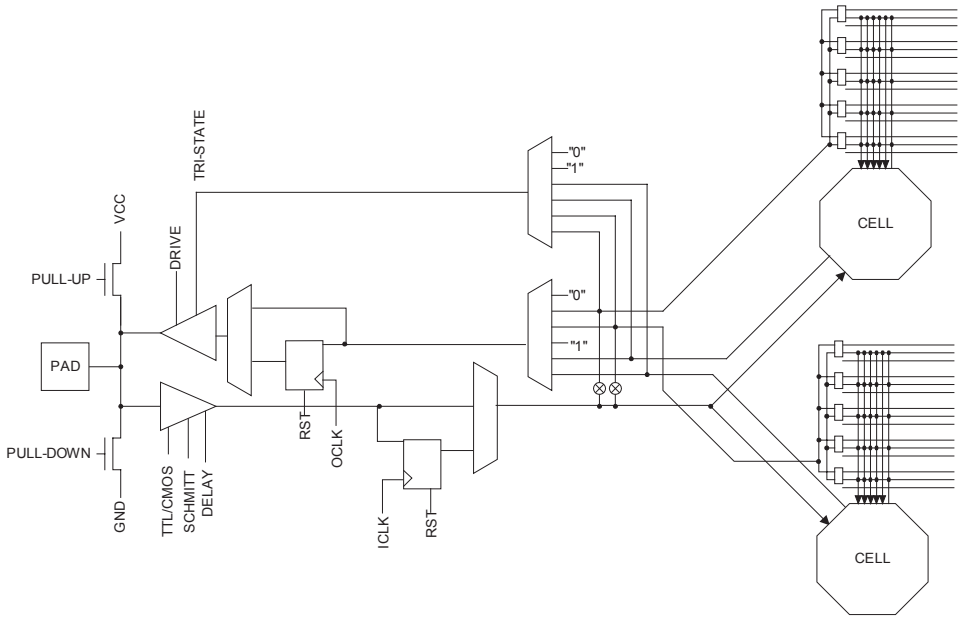


Figure 13. West Secondary I/O (Mirrored for East I/O)



Absolute Maximum Ratings – 3.3V Commercial/Industrial*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-0.5V to V_{CC} +7V
Supply Voltage (V_{CC})	-0.5V to +7.0V
Maximum Soldering Temp. (10 sec. @ 1/16 in.)	250°C
ESD (R_{ZAP} = 1.5K, C_{ZAP} = 100 pF)	2000V

*NOTICE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those listed under operating conditions is not implied. Exposure to Absolute Maximum Rating conditions for extended periods of time may affect device reliability.

DC and AC Operating Range – 3.3V Operation

		Commercial	Industrial
Operating Temperature (Case)		0°C - 70°C	-40°C - 85°C
V_{CC} Power Supply		3.3V ± 0.3V	3.3V ± 0.3V
Input Voltage Level (CMOS)	High (V_{IHC})	70% - 100% V_{CC}	70% - 100% V_{CC}
	Low (V_{ILC})	0 - 30% V_{CC}	0 - 30% V_{CC}

DC Characteristics – 3.3V Operation Commercial/Industrial

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V_{IH}	High-level Input Voltage	CMOS	0.7 V_{CC}		5.5V	V
V_{IL}	Low-level Input Voltage	CMOS	-0.3		30% V_{CC}	V
V_{OH}	High-level Output Voltage	I_{OH} = 4 mA V_{CC} = V_{CC} minimum	2.1			V
		I_{OH} = 12 mA V_{CC} = 3.0V	2.1			V
		I_{OH} = 16 mA V_{CC} = 3.0V	2.1			V
V_{OL}	Low-level Output Voltage	I_{OL} = -4 mA V_{CC} = 3.0V			0.4	V
		I_{OL} = -12 mA V_{CC} = 3.0V			0.4	V
		I_{OL} = -16 mA V_{CC} = 3.0V			0.4	V
I_{IH}	High-level Input Current	V_{IN} = V_{CC} Maximum			10.0	µA
		With pull-down, V_{IN} = V_{CC}	75.0	150.0	300.0	µA
I_{IL}	Low-level Input Current	V_{IN} = V_{SS}	-10.0			µA
		With pull-up, V_{IN} = V_{SS}	-300.0	-150.0	-75.0	µA
I_{OZH}	High-level Tri-state Output Leakage Current	Without pull-down, V_{IN} = V_{CC} Maximum			10.0	µA
		With pull-down, V_{IN} = V_{CC} Maximum	75.0	150.0	300.0	µA
I_{OZL}	Low-level Tri-state Output Leakage Current	Without pull-up, V_{IN} = V_{SS}	-10.0			mA
		With pull-up, V_{IN} = V_{SS}	CON = -500 µA TO -125 µA	-150.0	CON = -500 µA TO -125 µA	µA
I_{CC}	Standby Current Consumption	Standby, unprogrammed		0.6	1.0	mA
C_{IN}	Input Capacitance	All pins			10.0	pF

Note: 1. Parameter based on characterization and simulation; it is not tested in production.

Power-On Power Supply Requirements

Atmel FPGAs require a minimum rated power supply current capacity to insure proper initialization, and the power supply ramp-up time does affect the current required. A fast ramp-up time requires more current than a slow ramp-up time.

Table 3. Power-On Power Supply Requirements[1]

Device	Description	Maximum Current[2][3]
AT40K05AL AT40K10AL	Maximum Current Supply	50 mA
AT40K20AL AT40K40AL	Maximum Current Supply	100 mA

Notes:
1. This specification applies to Commercial and Industrial grade products only.
2. Devices are guaranteed to initialize properly at 50% of the minimum current listed above. A larger capacity power supply may result in a larger initialization current.
3. Ramp-up time is measured from 0 V DC to 3.6 V DC. Peak current required lasts less than 2 ms, and occurs near the internal power on reset threshold voltage.

AC Timing Characteristics – 3.3V Operation

Delays are based on fixed loads and are described in the notes.
Maximum times based on worst case: V_{CC} = 3.0V, temperature = 70°C
Minimum times based on best case: V_{CC} = 3.6V, temperature = 0°C
Maximum delays are the average of t_{PDLH} and t_{PDHL}.

All input IO characteristics measured from a V_{IH} of 50% of V_{DD} at the pad (CMOS threshold) to the internal V_{IH} of 50% of V_{DD}. All output IO characteristics are measured as the average of t_{PDLH} and t_{PDHL} to the pad V_{IH} of 50% of V_{DD}.

Cell Function	Parameter	Path	-1	Units	Notes
Repeaters					
Repeater	t_{PD} (Maximum)	L -> E	1.3	ns	1 unit load
Repeater	t_{PD} (Maximum)	E -> E	1.3	ns	1 unit load
Repeater	t_{PD} (Maximum)	L -> L	1.3	ns	1 unit load
Repeater	t_{PD} (Maximum)	E -> L	1.3	ns	1 unit load
Repeater	t_{PD} (Maximum)	E -> IO	0.8	ns	1 unit load
Repeater	t_{PD} (Maximum)	L -> IO	0.8	ns	1 unit load

All input IO characteristics measured from a V_{IH} of 50% of V_{DD} at the pad (CMOS threshold) to the internal V_{IH} of 50% of V_{DD}. All output IO characteristics are measured as the average of t_{PDLH} and t_{PDHL} to the pad V_{IH} of 50% of V_{DD}.

Cell Function	Parameter	Path	-1	Units	Notes
IO					
Input	t_{PD} (Maximum)	pad -> x/y	1.2	ns	No extra delay
Input	t_{PD} (Maximum)	pad -> x/y	3.6	ns	1 extra delay
Input	t_{PD} (Maximum)	pad -> x/y	7.3	ns	2 extra delays
Input	t_{PD} (Maximum)	pad -> x/y	10.8	ns	3 extra delays
Output, Slow	t_{PD} (Maximum)	x/y/E/L -> pad	5.9	ns	50 pf load
Output, Medium	t_{PD} (Maximum)	x/y/E/L -> pad	4.8	ns	50 pf load
Output, Fast	t_{PD} (Maximum)	x/y/E/L -> pad	3.9	ns	50 pf load
Output, Slow	t_{PZX} (Maximum)	oe -> pad	6.2	ns	50 pf load
Output, Slow	t_{PXZ} (Maximum)	oe -> pad	1.3	ns	50 pf load
Output, Medium	t_{PZX} (Maximum)	oe -> pad	4.8	ns	50 pf load
Output, Medium	t_{PXZ} (Maximum)	oe -> pad	1.9	ns	50 pf load
Output, Fast	t_{PZX} (Maximum)	oe -> pad	3.7	ns	50 pf load
Output, Fast	t_{PXZ} (Maximum)	oe -> pad	1.6	ns	50 pf load

AC Timing Characteristics – 3.3V Operation

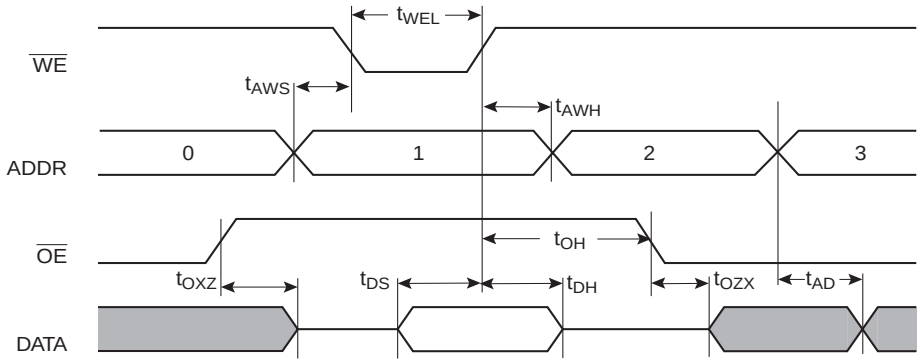
Delays are based on fixed loads and are described in the notes.
Maximum times based on worst case: V_{CC} = 3.0V, temperature = 70°C
Minimum times based on best case: V_{CC} = 3.6V, temperature = 0°C
Maximum delays are the average of t_{PDLH} and t_{PDHL}.

Clocks and Reset Input buffers are measured from a V_{IH} of 1.5V at the input pad to the internal V_{IH} of 50% of V_{CC}.
Maximum times for clock input buffers and internal drivers are measured for rising edge delays only.

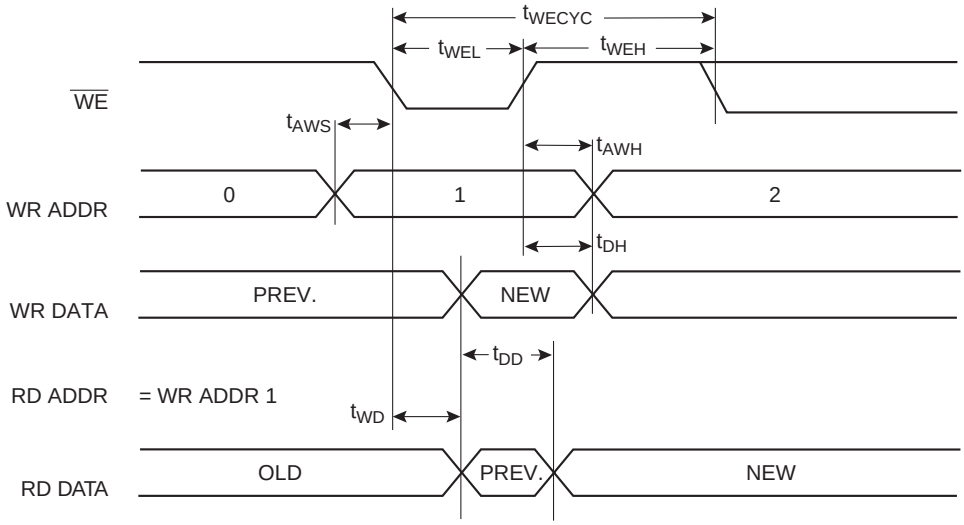
Cell Function	Parameter	Path	Device	-1	Units	Notes
Global Clocks and Set/Reset						
GCLK Input Buffer	t_{PD} (Maximum)	pad -> clock pad -> clock pad -> clock pad -> clock	AT40K05AL AT40K10AL AT40K20AL AT40K40AL	1.1 1.2 1.2 1.4	ns ns ns ns	Rising edge clock
FCLK Input Buffer	t_{PD} (Maximum)	pad -> clock pad -> clock pad -> clock pad -> clock	AT40K05AL AT40K10AL AT40K20AL AT40K40AL	0.7 0.8 0.8 0.8	ns ns ns ns	Rising edge clock
Clock Column Driver	t_{PD} (Maximum)	clock -> colclk clock -> colclk clock -> colclk clock -> colclk	AT40K05AL AT40K10AL AT40K20AL AT40K40AL	0.8 0.9 1.0 1.1	ns ns ns ns	Rising edge clock
Clock Sector Driver	t_{PD} (Maximum)	colclk -> secclk colclk -> secclk colclk -> secclk colclk -> secclk	AT40K05AL AT40K10AL AT40K20AL AT40K40AL	0.5 0.5 0.5 0.5	ns ns ns ns	Rising edge clock
GSRN Input Buffer	t_{PD} (Maximum)	pad -> GSRN pad -> GSRN pad -> GSRN pad -> GSRN	AT40K05AL AT40K10AL AT40K20AL AT40K40AL	3.0 3.7 4.3 5.6	ns ns ns ns	From any pad to Global Set/Reset network
Global Clock to Output	t_{PD} (Maximum)	clock pad -> out clock pad -> out clock pad -> out clock pad -> out	AT40K05AL AT40K10AL AT40K20AL AT40K40AL	8.3 8.4 8.6 8.8	ns ns ns ns	Rising edge clock Fully loaded clock tree Rising edge DFF 20 mA output buffer 50 pf pin load
Fast Clock to Output	t_{PD} (Maximum)	clock pad -> out clock pad -> out clock pad -> out clock pad -> out	AT40K05AL AT40K10AL AT40K20AL AT40K40AL	7.9 8.0 8.1 8.3	ns ns ns ns	Rising edge clock Fully loaded clock tree Rising edge DFF 20 mA output buffer 50 pf pin load

FreeRAM Asynchronous Timing Characteristics

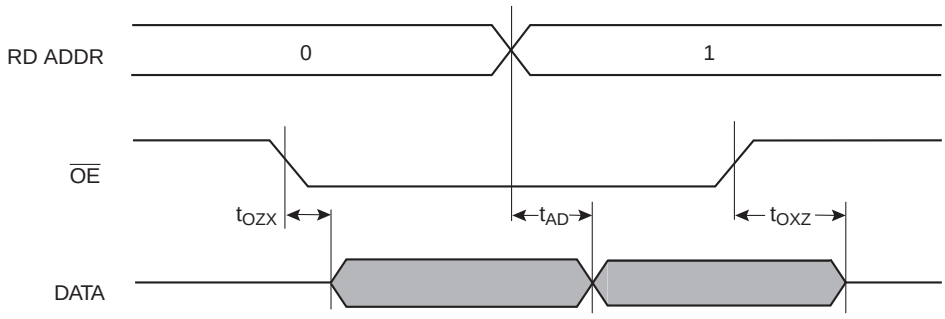
Single-port Write/Read



Dual-port Write with Read



Dual-port Read



AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Right Side (Bottom to Top)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
			I/O243					
			I/O244					
I/O83	I/O123	I/O163	I/O245		67	94	134	154
I/O84	I/O124	I/O164	I/O246			95	135	155
			GND					
	I/O125	I/O165	I/O247				136	156
	I/O126	I/O166	I/O248				137	157
		I/O167	I/O249					
		I/O168	I/O250					
			I/O251					
			I/O252					
			VCC					
		GND	GND					158
		I/O169	I/O253					
		I/O170	I/O254					
			I/O255					
			I/O256					
			I/O257					
			I/O258					
			GND					
I/O85 (D2)	I/O127 (D2)	I/O171 (D2)	I/O259 (D2)	67	68	96	138	159
I/O86	I/O128	I/O172	I/O260	68	69	97	139	160
	VCC	VCC	VCC					161
I/O87	I/O129	I/O173	I/O261			98	140	162
I/O88, FCK4	I/O130, FCK4	I/O174, FCK4	I/O262, FCK4			99	141	163
	I/O131	I/O175	I/O263					164
	I/O132	I/O176	I/O264					165
GND	GND	GND	GND			100	142	166
		I/O177	I/O265					
		I/O178	I/O266					
	I/O133	I/O179	I/O267					167
	I/O134	I/O180	I/O268					168
			I/O269					

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Right Side (Bottom to Top)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
			I/O270					
			GND					
	I/O135	I/O181	I/O271				143	169
	I/O136	I/O182	I/O272				144	170
I/O89	I/O137	I/O183	I/O273				145	171
I/O90	I/O138	I/O184	I/O274				146	172
			I/O275					
			I/O276					
		GND	GND					
		VCC	VCC					
I/O91 (D1)	I/O139 (D1)	I/O185 (D1)	I/O277 (D1)	69	70	101	147	173
I/O92	I/O140	I/O186	I/O278	70	71	102	148	174
			I/O279					
			I/O280					
			I/O281					
			I/O282					
			GND					
		I/O187	I/O283					
		I/O188	I/O284					
I/O93	I/O141	I/O189	I/O285			103	149	175
I/O94	I/O142	I/O190	I/O286			104	150	176
I/O95 (D0)	I/O143 (D0)	I/O191 (D0)	I/O287 (D0)	71	72	105	151	177
I/O96, GCK6 ($\overline{\text{CSOUT}}$)	I/O144, GCK6 ($\overline{\text{CSOUT}}$)	I/O192, GCK6 ($\overline{\text{CSOUT}}$)	I/O288, GCK6 ($\overline{\text{CSOUT}}$)	72	73	106	152	178
CCLK	CCLK	CCLK	CCLK	73	74	107	153	179
VCC	VCC	VCC	VCC	74	75	108	154	180
TSTCLK	TSTCLK	TSTCLK	TSTCLK	75	76	109	159	181

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Top Side (Right to Left)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
GND	GND	GND	GND	76	77	110	160	182
I/O97 (A0)	I/O145 (A0)	I/O193 (A0)	I/O289 (A0)	77	78	111	161	183
I/O98, GCK7 (A1)	I/O146, GCK7 (A1)	I/O194, GCK7 (A1)	I/O290, GCK7 (A1)	78	79	112	162	184
I/O99	I/O147	I/O195	I/O291			113	163	185
I/O100	I/O148	I/O196	I/O292			114	164	186
			I/O293					
			I/O294					
			GND					
			I/O295					
			I/O296					
I/O101 ($\overline{CS1}$,A2)	I/O149 ($\overline{CS1}$,A2)	I/O197 ($\overline{CS1}$,A2)	I/O297 ($\overline{CS1}$,A2)	79	80	115	165	187
I/O102 (A3)	I/O150 (A3)	I/O198 (A3)	I/O298 (A3)	80	81	116	166	188
		I/O199	I/O299					
		I/O200	I/O300					
		VCC	VCC					
		GND	GND					
	I/O151[1]	I/O201[1]	I/O301[1]	75[1] NC	76[1] NC	109[1] NC	159[1] NC	189[1] NC
	I/O152	I/O202	I/O302					190
I/O103	I/O153	I/O203	I/O303			117	167	191
I/O104[1]	I/O154	I/O204	I/O304				168	192
			I/O305					
			I/O306					
			GND					
			I/O307					
			I/O308					
	I/O155	I/O205	I/O309				169	193
	I/O156	I/O206	I/O310				170	194
		I/O207	I/O311					195
		I/O208	I/O312					
GND	GND	GND	GND			118	171	196

Note: 1. Shared with TSTCLK. No Connect.

Part/Package Availability and User I/O Counts (including Dual-function Pins)

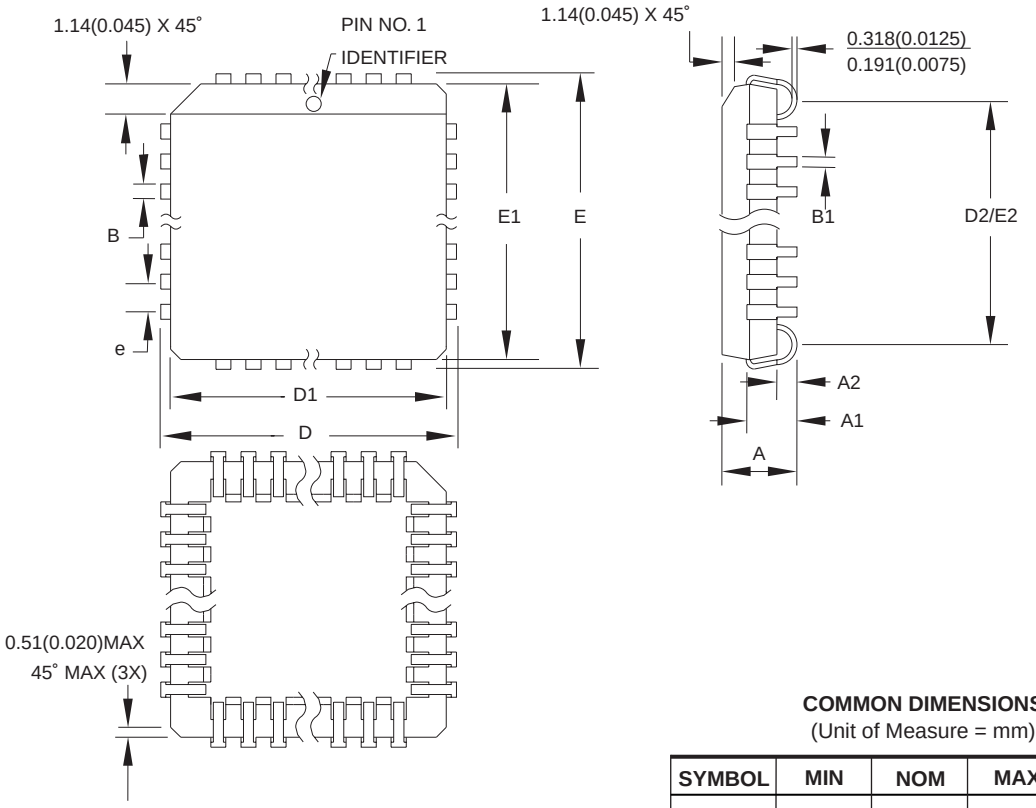
Package[1]	AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL
84 PLCC	62	62	–	62
100 TQFP	78	78	78	–
144 LQFP	114	114	114	114
208 PQFP	128	161	161	161
240 PQFP	–	–	–	193

Note: 1. Devices in same package are pin-to-pin compatible.

Package Type	
84J	84-lead, Plastic J-leaded Chip Carrier (PLCC)
100T1	100-lead, Thin (1.0 mm) Plastic Quad Flat Package (TQFP)
144L1	144-lead, Low-profile (1.4 mm) Plastic Quad Flat Package (LQFP)
208Q1	208-lead, Plastic Quad Flat Package (PQFP)
240Q1	240-lead, Plastic Quad Flat Package (PQFP)

Packaging Information

84J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

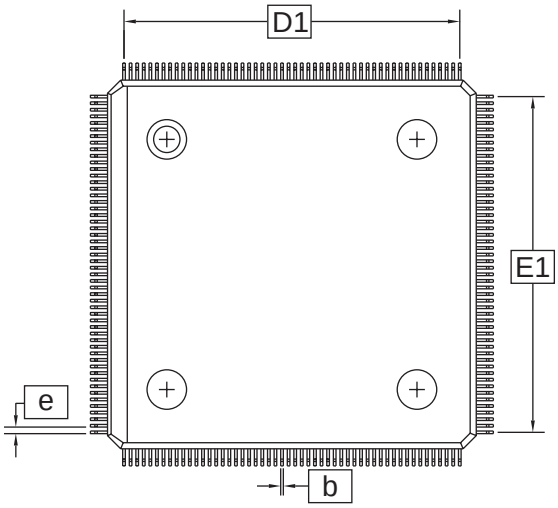
SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	–	4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	30.099	–	30.353	
D1	29.210	–	29.413	Note 2
E	30.099	–	30.353	
E1	29.210	–	29.413	Note 2
D2/E2	27.686	–	28.702	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-018, Variation AF.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

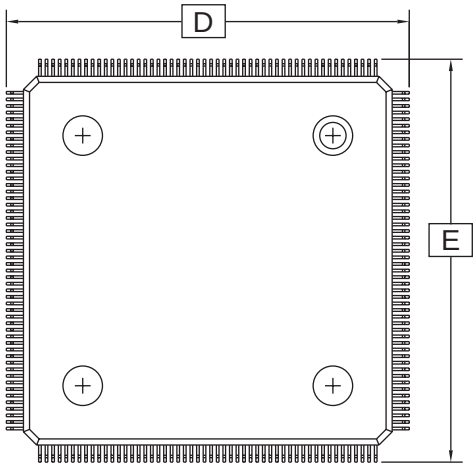
	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**84J**, 84-lead, Plastic J-leaded Chip Carrier (PLCC)	84J	B

208Q1 – PQFP



Top View

Side View



Bottom View

COMMON DIMENSIONS
(Unit of Measure = mm)

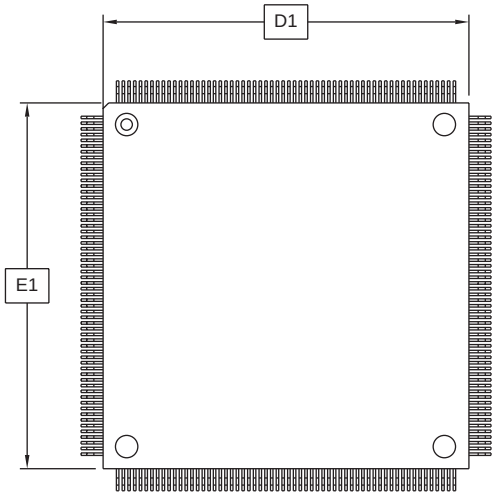
SYMBOL	MIN	NOM	MAX	NOTE
A1	0.25	–	0.50	
A2	3.20	3.40	3.60	
D		30.60 BSC		
D1		28.00 BSC		2, 3
E		30.60 BSC		
E1		28.00 BSC		2, 3
e		0.50 BSC		
b	0.17	–	0.27	4
L1		1.30 REF		

Notes:
1. This drawing is for general information only; refer to JEDEC Drawing MS-129, Variation FA-1, for proper dimensions, tolerances, datums, etc.
2. The top package body size may be smaller than the bottom package size by as much as 0.15 mm.
3. Dimensions D1 and E1 do not include mold protrusions. Allowable protrusion is 0.25 mm per side. D1 and E1 are maximum plastic body size dimensions including mold mismatch.
4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall not cause the lead width to exceed the maximum b dimension by more than 0.08 mm. Dambar cannot be located on the lower radius or the foot. Minimum space between protrusion and an adjacent lead is 0.07 mm.

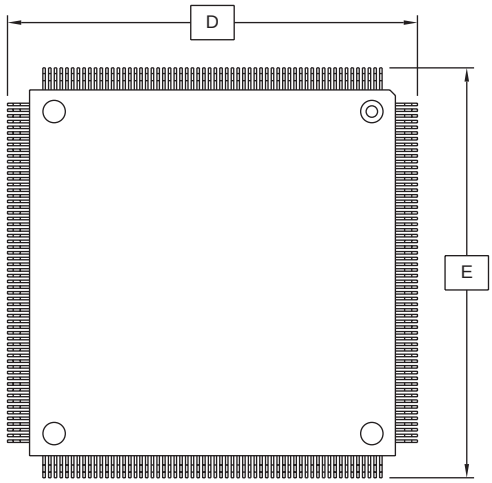
07/23/02

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**208Q1**, 208-lead (28 x 28 mm Body, 2.6 Form Opt.), Plastic Quad Flat Pack (PQFP)	208Q1	B

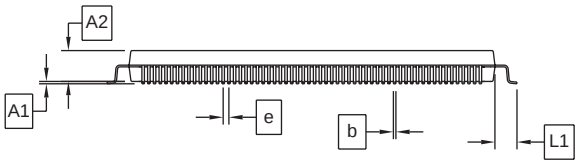
240Q1 – PQFP



Top View



Bottom View



Side View

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A1	0.25	–	0.50	
A2	3.20	3.40	3.60	
D		34.60 BSC		3
D1		32.00 BSC		2, 4
E		34.60 BSC		3
E1		32.00 BSC		2, 4
e		0.50 BSC		
b	0.17	–	0.27	5
L1		1.30 REF		

Notes:
1. This drawing is for general information only. Refer to JEDEC Drawing MS-029, Variation GA, for additional information.
2. All dimensioning and tolerancing conforms to ASME Y14.5M-1994.
3. To be determined at seating plane.
4. Dimensions D1 and E1 do not include mold protrusions. Allowable protrusion is 0.25 mm per side. D1 and E1 are maximum plastic body size dimensions including mold mismatch. Dimensions D1 and E1 shall be determined at datum plane.
5. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall not cause the lead width to exceed the maximum b dimension by more than 0.08 mm. Dambar cannot be located on the lower radius or the foot. The minimum space between protrusion and an adjacent lead shall not be less than 0.07 mm.

3/29/02

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**240Q1,** 240-lead, 32 x 32 mm Body, 2.6 Form Opt., Plastic Quad Flat Pack (PQFP)	240Q1	A